

Application No.: 10/826,261

Docket No.: 4459-147

AMENDMENTS TO THE SPECIFICATION:*Please amend the paragraph on page 4, beginning at line 26 as follows:*

The micromachine chip 120 is attached on a die pad 142 of a lead frame 140 by means of an adhesive 126. The adhesive 126 can be a conductive paste for electrically connecting the micromachine chip 120 to the die pad 142. The semiconductor package ~~[[110]]~~100 is provided with a plurality of solder pads 118 disposed on the two adjacent sides thereof, which will be described hereinafter, and electrically connected to the electrodes 112. The solder pad 118 is connected to a bump 114, such as a gold bump or a solder bump. The bumps 114 are individually disposed on a plurality of leads 144 of the lead frame 140. An encapsulant 130 encapsulates the micromachine chip 120, the semiconductor chip 110, the bumps 114, and the lead frame 140. The leads 144 and the die pad 142 of the lead frame 140 respectively have lower surfaces 148 and a lower surface 146 which are exposed out of and are flush with the encapsulant 130 for being connected to an external print circuit board (not shown). Therefore, the leads 144 are referred to Quad Flat No-lead (QFN)-type leads. The lower surface 146 of the die pad 142 can also be used for grounding or dissipating heat.

Please amend the paragraph on page 8, beginning at line 9 as follows:

Now referring to FIG. 18, it depicts a micromachine package 500' according to still another embodiment of the present invention. The micromachine package 500' is similar to the micromachine package 500, wherein the similar elements are designated with the same numerals. The micromachine package 500' is further provided with moveable structures 522' and electrodes 512' which both are disposed on a semiconductor chip 520 and electrically connected to a plurality of solder pads 518 of a lid ~~[[510]]~~510' by way of a plurality of solder balls 580.

Abstract:

Please replace the current Abstract with the following replacement/new Abstract